



Material Content Data Sheet



Sales Product Name		TDA4863G		Issued		19. July 2018		
MA#		MA001039034						
Package		PG-DSO-8-41		Weight*		81.24 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.391	4.17	4.17	41738	41738
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.673	0.83		8285	
wire	non noble metal	copper	7440-50-8	27.330	33.64	34.52	336408	345211
	noble metal	gold	7440-57-5	0.091	0.11	0.11	1126	1126
	encapsulation	organic material	carbon black	1333-86-4	0.142	0.17		1742
encapsulation	plastics	epoxy resin	-	4.575	5.63		56319	
	inorganic material	silicondioxide	60676-86-0	42.453	52.27	58.07	522547	580608
leadfinish	non noble metal	tin	7440-31-5	0.824	1.01	1.01	10143	10143
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1102	1102
glue	plastics	acrylic resin	-	0.326	0.40		4014	
	noble metal	silver	7440-22-4	1.305	1.61	2.01	16058	20072
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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